

WHAT IS CLAIMED IS:

1. An apparatus for testing an electronic component, comprising:
 - a substrate having at least one cavity on the upper surface thereof for accommodating an electronic component;
 - at least one connecting conductor disposed at an interior of or on a lower surface of the substrate, and extending from under the cavity in a direction that is substantially perpendicular to a thickness direction of the substrate;
 - a through-hole electrode disposed in the vicinity of the cavity, having a lower end that is electrically connected to the connecting conductor, and having an upper end that is attached to the upper surface of the substrate; and
 - a terminal pad disposed on the upper surface of the substrate and electrically connected to the upper end of the through-hole electrode.
2. An apparatus for testing an electronic component according to Claim 1, wherein said at least one connecting conductor includes a plurality of connecting conductors corresponding to electrodes of the electronic component, the plurality of connecting conductors are separated under the cavity, and the through-hole electrode and the terminal pad are provided for each of said plurality of connecting conductors.
3. An apparatus for testing an electronic component according to Claim 2, further comprising a suction hole having a diameter that is smaller than that of the cavity, the suction hole opposing the cavity via the connecting conductor, and extending toward an exterior of the substrate.
4. An apparatus for testing an electronic component according to Claim 3, wherein the suction hole passes through the connecting conductor.

5. An apparatus for testing an electronic component according to Claim 1, wherein a plurality of testing units, each having the cavity, the connecting conductor, and the terminal pad, are arranged along a circumferential direction.

6. An apparatus for testing an electronic component according to Claim 1, wherein a plurality of testing units, each having the cavity, the connecting conductor, and the terminal pad, are arranged in a matrix.

7. An apparatus for testing an electronic component according to Claim 1, wherein said substrate includes at least one printed board and an insulating base material that are stacked.

8. An apparatus for testing an electronic component according to Claim 1, wherein said insulating base material defines a lower surface of the substrate.

9. An apparatus for testing an electronic component according to Claim 1, wherein said terminal pad is made of a copper layer coated with a nickel layer.

10. An apparatus for testing an electronic component according to Claim 1, wherein an inclined surface is provided in the substrate at a top opening of the at least one cavity.

11. A method for testing an electronic component using an apparatus for testing an electronic component according to Claim 1, comprising the steps of:

inserting the electronic component into the cavity to enable a first electrode of the electronic component to contact the connecting conductor;
and

attaching a probe to the terminal pad for measuring the characteristics of the electronic component.